

Title (en)

CASTING RESIN, MOULDING MATERIAL THEREFROM, USE THEREFOR, AND ELECTRICAL INSULATION

Title (de)

GIESSHARZ, FORMSTOFF DARAUS, VERWENDUNG DAZU UND EINE ELEKTRISCHE ISOLIERUNG

Title (fr)

RÉSINE DE COULÉE, MATÉRIAU DE MOULAGE OBTENU À PARTIR DE CETTE DERNIÈRE, SON UTILISATION ET UNE ISOLATION ÉLECTRIQUE

Publication

EP 3931849 A1 20220105 (DE)

Application

EP 20714944 A 20200318

Priority

- DE 102019204191 A 20190327
- EP 2020057499 W 20200318

Abstract (en)

[origin: WO2020193323A1] The invention relates to a novel composition of a casting resin and to the use thereof in hot-curing electrical potting, as used for example in the production of insulation, for example for gas-insulated switchgears, electrical components such as transformers, insulators, capacitors, coils and modules. The invention also relates to a moulding material which is obtainable from the casting resin, to electrical insulation which comprises this moulding material, and to the use of such a moulding material. In particular the tetramodality of the microfillers used together with the average particle sizes classified into decimal powers results in an excellent packing density and exhibits surprisingly good workability and flow behaviour at the highest filler contents up to 95 wt%. With the invention, it is possible for the first time to use such high-filler and thus highly thermally conductive casting resins in the aforementioned systems for automatic pressure gelation processes and/or in a (vacuum) circulation casting system.

IPC 8 full level

H01B 3/40 (2006.01); **C08K 3/22** (2006.01); **C08K 3/38** (2006.01)

CPC (source: EP)

H01B 3/40 (2013.01); **C08K 2003/2227** (2013.01); **C08K 2003/385** (2013.01)

C-Set (source: EP)

1. **C08K 2003/2227** + **C08L 63/00**
2. **C08K 2003/385** + **C08L 63/00**

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

WO 2020193323 A1 20201001; CN 113906524 A 20220107; CN 113906524 B 20240920; DE 102019204191 A1 20201001; EP 3931849 A1 20220105

DOCDB simple family (application)

EP 2020057499 W 20200318; CN 202080039269 A 20200318; DE 102019204191 A 20190327; EP 20714944 A 20200318